N3T080MP330

3300 V 80 m Ω Silicon Carbide MOSFET

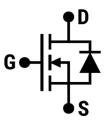
V _{DS}	I _D	R _{DS(on)}	Package
3300 V	34 A	80 mΩ	Bare Die

Features

- State-of-the-art SiC MOSFET technology
- Reliable gate oxide process
- Ultra-low output capacitance
- Best-in-class figure-of-merits, $[R_{on}{}^*C_{oss}]$ and $[R_{on}{}^*C_{rss}]$
- Stable switching characteristics up to 175 °C

Benefits

- Higher system efficiency
- Reduced cooling requirements
- Increased power density
- Increased system switching frequency
- Enhanced system reliability
- Reduced total harmonic distortion





Applications

- Motor drives
- Solar PV inverters
- EV onboard chargers
- Server power supplies
- Energy storage systems
- EV fast charging stations
- Solid-state power controllers
- · Uninterruptible power supplies

Maximum Ratings

Parameter	Symbol	Test Conditions	Min.	Тур.	Max	Unit	Note
Drain-Source Voltage	V _{(BR)DSS}	T _C = 25 °C	3300	-	-	٧	
Gate-Source Voltage	V _{GS(max)}		-10	-	25	٧	
	$V_{GS,op}$	Recommended Operation	-	-5/+20	ı		
Continuous Drain Current	l _D	V _{GS} = 20 V, T _C = 25 °C	-	-	34	- A	Fig.
		V _{GS} = 20 V, T _C = 100 °C	-	-	24		13
Pulsed Drain Current	I _{D(pulse)}	T _C = 25 °C	-	-	80	Α	Fig. 12
Power Dissipation	P _{tot}	T _C = 25 °C	-	-	288	w	Fig. 14
Operating and Storage Temperature	T _J , T _{stg}		-55	-	175	°C	

Thermal and Bare Die Characteristics

Parameter	Symbol	Comment	Min.	Тур.	Max.	Unit	Note
Thermal Resistance, Junction to Case	R _{thJC}	Based on TO-247-4L packaged die measurements	-	0.32	0.52	°C/W	Fig. 11
Thermal Resistance, Junction to Ambient	R _{thJA}	Based on TO-247-4L packaged die measurements	-	•	40	°C/W	
Bare Die Thickness	Wdie		335	360	385	μm	
Top Metal Thickness	W _{top}	Al/Cu metallization	-	5.0	ı	μm	
Bottom Metal Thickness	W _{bottom}	Ag metallization	-	1.0	-	μm	

Electrical Characteristics (T_c = 25 °C unless otherwise specified)

STATIC CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	Note
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 100 μA	3300	-	-	٧	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 3300 V, V _{GS} = 0 V	-	1	100	μА	
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = 10 mA	1.8	2.5	3	V	
Gate-Source Leakage Current	I _{GSS}	V _{GS} = -10 / +25 V, V _{DS} = 0 V	ı	ı	±100	nA	
Transconductance	9fs	V _{DS} = 10 V, I _D = 20 A	-	9.8	-	s	Fig. 8
Drain-Source On-State Resistance		V _{GS} = 20 V, I _D = 20 A	-	79	90	mΩ	Fig. 1
	R _{DS(on)}	V _{GS} = 20 V, I _D = 20 A, T _C = 175 °C	ı	252	-	mΩ	Fig. 3
		V _{GS} = 18 V, I _D = 20 A	-	81	-	mΩ	Fig. 1
		V _{GS} = 18 V, I _D = 20 A, T _C = 175 °C	-	253	-	mΩ	Fig. 3

DYNAMIC CHARACTERISTICS

Note: Based on TO-247-4L packaged die measurements

Parameter	Symbol	Test Conditions	Min.	Тур.	Max	Unit	Note
Input Capacitance	C _{iss}		-	3830	-	pF	Fig. 10
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, } V_{DS} = 1700 \text{ V,}$ $V_{AC} = 25 \text{ mV, } f = 100 \text{ kHz}$	-	53.5	-		
Reverse Capacitance	C _{rss}		ı	3.35	-		
Gate-Source Charge	Q _{GS}		ı	30	-	nC	
Gate-Drain Charge	Q_{GD}	$V_{DS} = 1700 \text{ V},$ $V_{GS} = -5 / +20 \text{ V}, I_D = 20$ A	1	28	-		Fig. 15
Total Gate Charge	Q _G	[ı	168	-		
Internal Gate Resistance	R _{G(int)}	V _{AC} = 25 mV, f = 1 MHz	-	1.1	-	Ω	
Turn-On Switching Energy	E _{ON}	V _{DD} = 1700 V, I _D = 20 A,	ı	1283	ı	μJ	F: 10
Turn-Off Switching Energy	E _{OFF}	$V_{GS} = -5 / +20 \text{ V, } R_{G(ext)} = 10 \Omega,$	ı	217	ı		Fig. 16 Fig. 17 Fig. 18
Total Switching Energy	Етот	L = 500 μH	ı	1500	-		I-ig. 16
Turn-On Delay Time	t _{d(on)}	V_{DD} = 1700 V, I_{D} = 20 A, V_{GS} = -5 / +20 V, $R_{G(ext)}$ = 10 Ω, L = 500 μH Timing relative to V_{DS} Inductive Load	-	43	-		
Rise Time	t _r		-	29	-		Fig. 10
Turn-Off Delay Time	t _{d(off)}		-	74	-	ns	Fig. 19
Fall Time	t _f		-	22	-		

BODY DIODE CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min.	Тур.	Max	Unit	Note
Diode Forward Voltage	V_{SD}	V _{GS} = -5 V, I _{SD} = 20 A	-	4.8	ı	V	Fig. 20
		V _{GS} = -5 V, I _{SD} = 20 A, T _J = 175 °C	-	4.1	ı	>	Fig. 21
Continuous Diode Forward Current	Is	V _{GS} = -5 V	-	44	ı	A	
Reverse Recovery Time	t _{rr}	V _R = 1700 V, I _{SD} = 20 A, V _{GS} = -5 V, di _F /dt = 1000 A/μs	-	9	ı	ns	
Reverse Recovery Charge	Q _{rr}		-	226	ı	nC	
Peak Reverse Recovery Current	I _{RRM}		-	25		A	

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Typical Performance

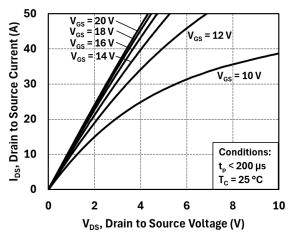


Figure 1: Output Characteristics at 25 °C

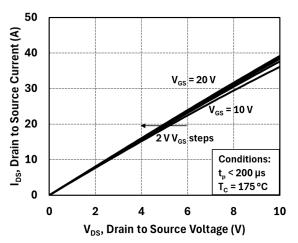


Figure 3: Output Characteristics at 175 °C

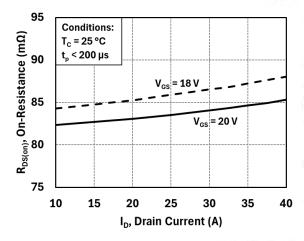


Figure 5: On-Resistance vs. Drain Current

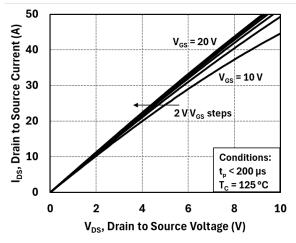


Figure 2: Output Characteristics at 125 °C

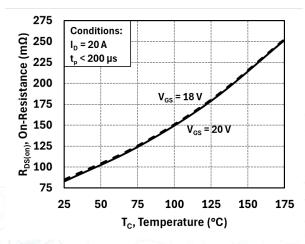


Figure 4: On-Resistance vs. Temperature

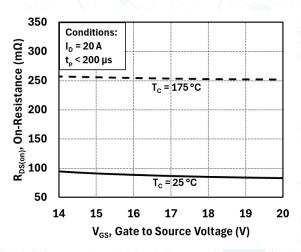


Figure 6: On-Resistance vs. Gate Voltage

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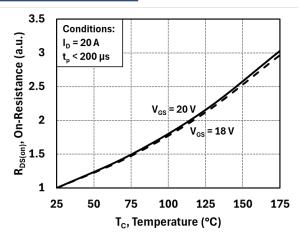


Figure 7: Normalized On-Resistance vs. Temperature

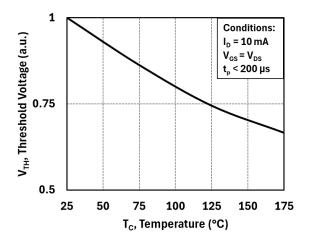


Figure 9: Threshold Voltage vs. Temperature

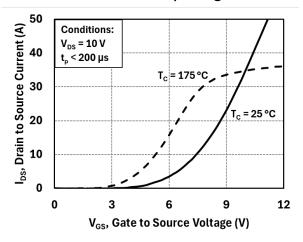


Figure 8: Transfer Characteristics

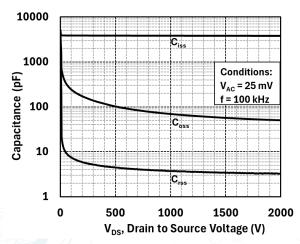


Figure 10: Capacitances vs. Drain-Source Voltage (0-1000 V)

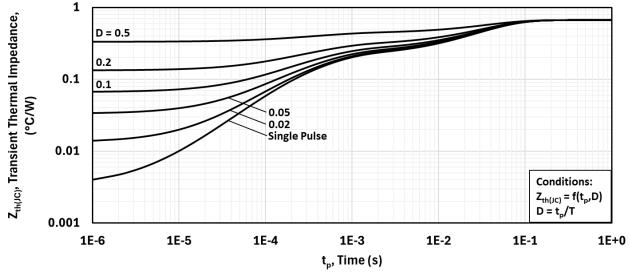


Figure 11: Transient Thermal Impedance

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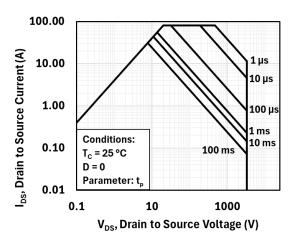


Figure 12: Safe Operating Area

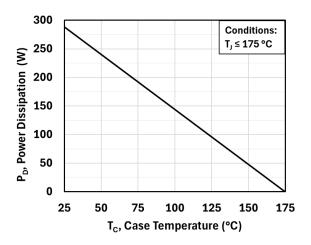


Figure 14: Power De-rating Curve

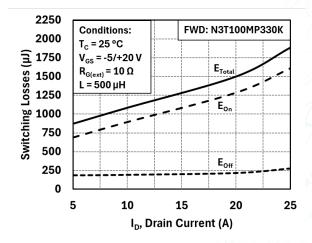


Figure 16: Inductive Switching Energy vs. Drain Current $(V_{DD} = 1700 \text{ V})$

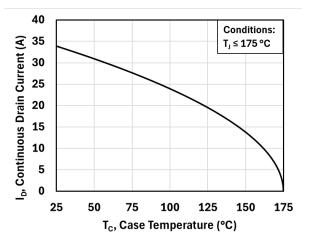


Figure 13: Current De-rating Curve

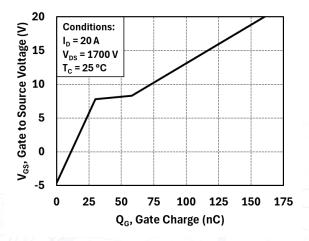


Figure 15: Gate Charge Characteristics

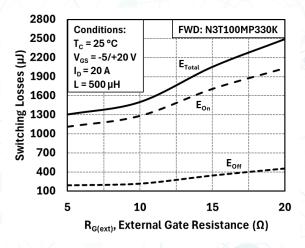


Figure 17: Inductive Switching Energy vs. $R_{G(ext)}$ (V_{DD} = 1700 V)



Typical Performance

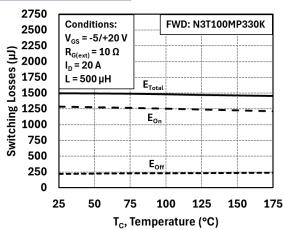


Figure 18: Inductive Switching Energy vs. Temperature $(V_{DD} = 1700 \text{ V})$

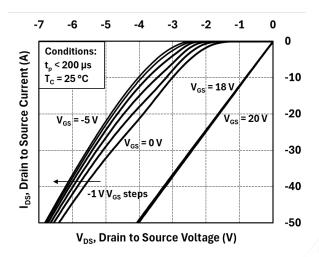


Figure 20: Body Diode Characteristics at 25 °C

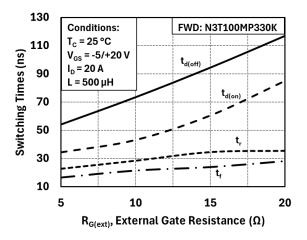


Figure 19: Switching Times vs. $R_{G(ext)}$ (V_{DD} = 1700 V)

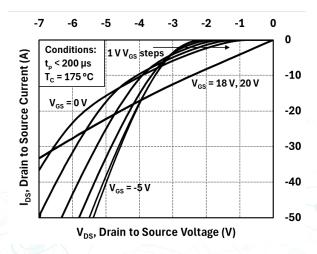


Figure 21: Body Diode Characteristics at 175 °C

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Dynamic Testing Circuit Schematics

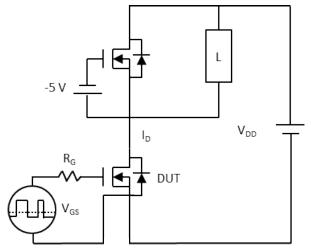


Figure 22: Inductive Load Switching Test Circuit

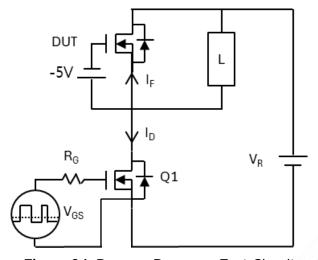


Figure 24: Reverse Recovery Test Circuit

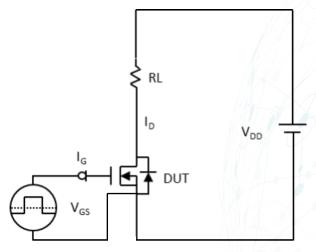


Figure 26: Gate Charge Test Circuit

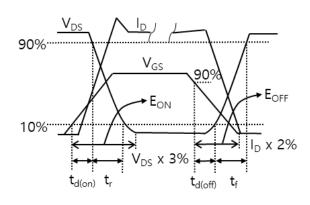


Figure 23: Inductive Load Switching Test Waveforms

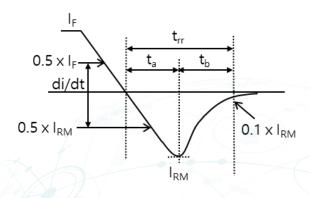


Figure 25: Body Diode Reverse Recovery Test Waveforms

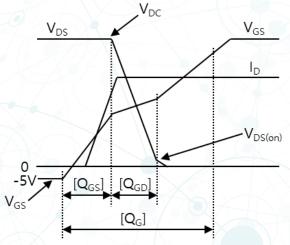


Figure 27: Gate Charge Test Waveforms

Bare Die Dimensions Dimensions in µm **Gate Pad**

Source Pads

Drain Pad on the

backside of the bare die

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